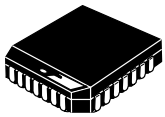
Quad 4-Input OR/NOR Gate

MC10E101
MC100E101

The MC10E/100E101 is a quad 4-input OR/NOR gate.

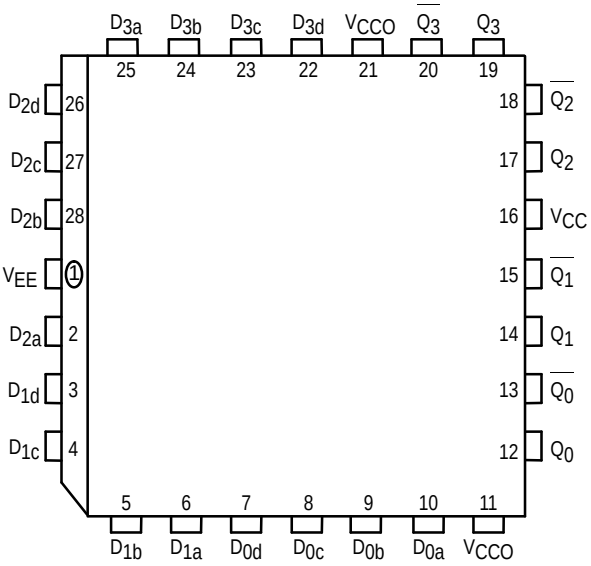
- 500ps Max. Propagation Delay
- Extended 100E V_{EE} Range of – 4.2V to – 5.46V
- 75kΩ Input Pulldown Resistors

QUAD 4-INPUT
OR/NOR GATE



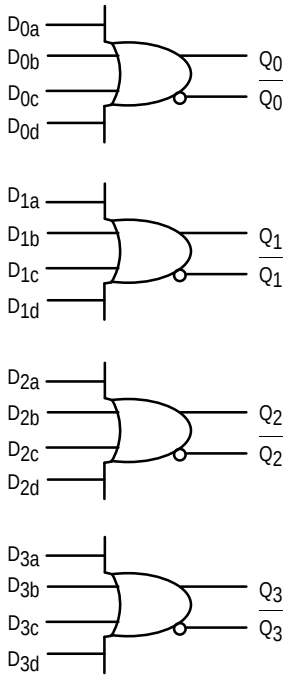
FN SUFFIX
PLASTIC PACKAGE
CASE 776-02

Pinout: 28-Lead PLCC (Top View)



* All V_{CC} and V_{CCO} pins are tied together on the die.

LOGIC DIAGRAM



PIN NAMES

Pin	Function
$D_{0a} - D_{3d}$	Data Inputs
$Q_0 - Q3$	True Outputs
$\overline{Q_0} - \overline{Q_3}$	Inverting Outputs

DC CHARACTERISTICS (V_{EE} = V_{EE}(min) to V_{EE}(max); V_{CC} = V_{CCO} = GND)

		0°C			25°C			85°C				
Symbol	**Characteristic**	**min**	**typ**	**max**	**min**	**typ**	**max**	**min**	**typ**	**max**	**Unit**	**Condition**
I_{IH}	Input HIGH Current			150			150			150	μA	
I_{EE}	Power Supply Current										mA	
	10E		30	36		30	36		30	36		
	100E		30	36		30	36		35	42		

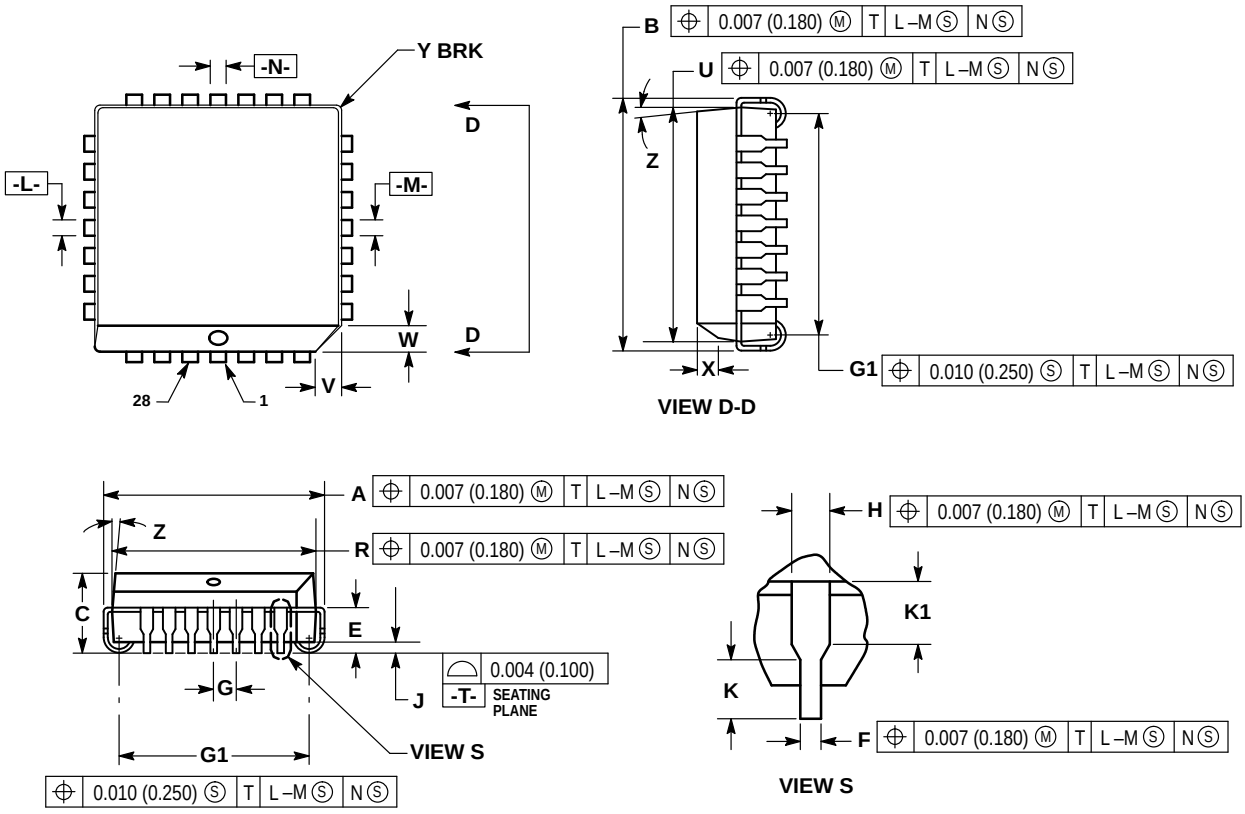
AC CHARACTERISTICS (V_{EE} = V_{EE}(min) to V_{EE}(max); V_{CC} = V_{CCO} = GND)

		0°C			25°C			85°C				
Symbol	**Characteristic**	**min**	**typ**	**max**	**min**	**typ**	**max**	**min**	**typ**	**max**	**Unit**	**Condition**
t_{PLH}	Propagation Delay to Output										ps	
t_{PHL}	D to Q	200	350	500	200	350	500	200	350	500		
t_{SKEW}	Within-Device Skew		50			50			50		ps	1
t_{SKEW}	Within-Gate Skew		25			25			25			2
t_r	Rise/Fall Time										ps	
t_f	20 - 80%	300	380	575	300	380	575	300	380	575		

1. Within-device skew is defined as identical transitions on similar paths through a device.
2. Within-gate skew is defined as the variation in propagation delays of a gate when driven from its different inputs.

OUTLINE DIMENSIONS

FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 776–02
ISSUE D



NOTES:
1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIM G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
3. DIM R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	—	1.02	—

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